



QUALIFICATION TESTING OF 3D-PRINTED LOOP HEAT PIPE WITH DEPLOYABLE RADIATOR

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Presented By
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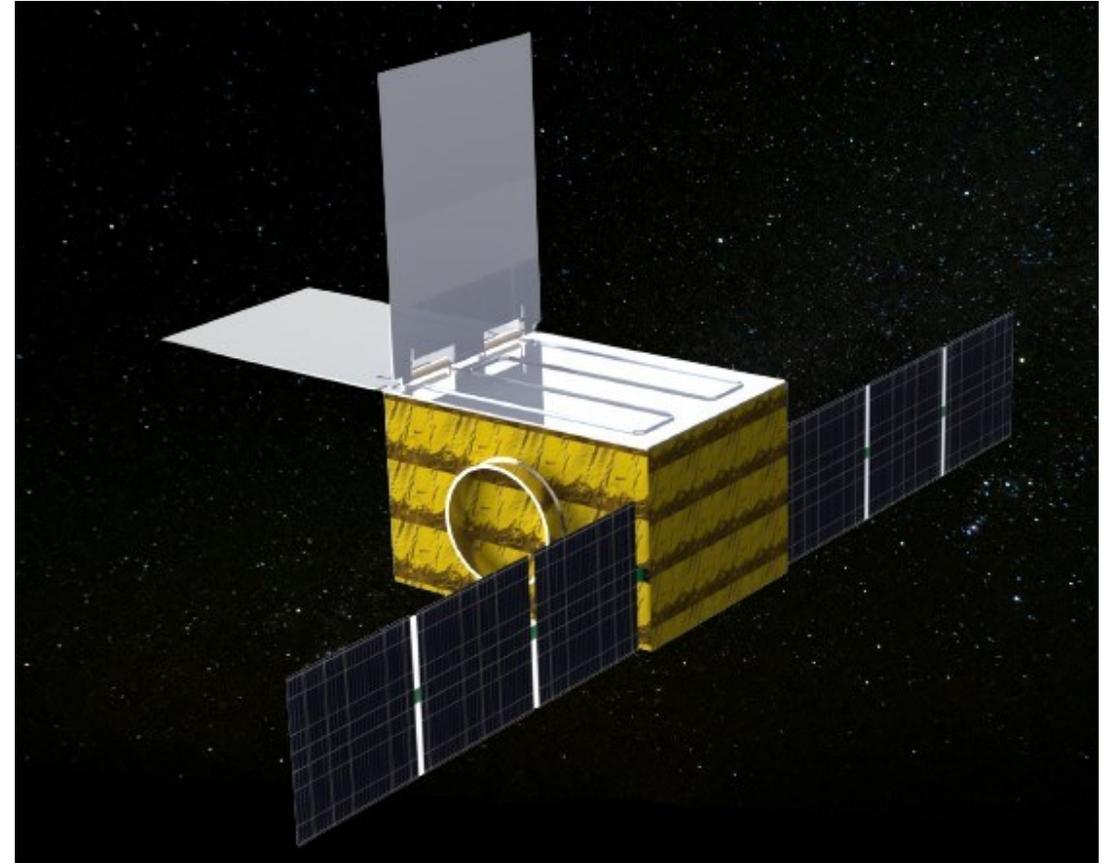


Agenda



- Motivation
- 3DP LHP and DRP Construction
- Laboratory Testing
- Vacuum Chamber Testing
- Next Steps

- The AFRL is interested in increasing the heat rejection capabilities for SmallSats
- Rejecting more heat requires a deployable radiator panel (DRP), but current solutions have a high thermal resistance
- The 3DP Loop Heat Pipe (LHP) is ideal for this application because of its lower cost and reduced lead time



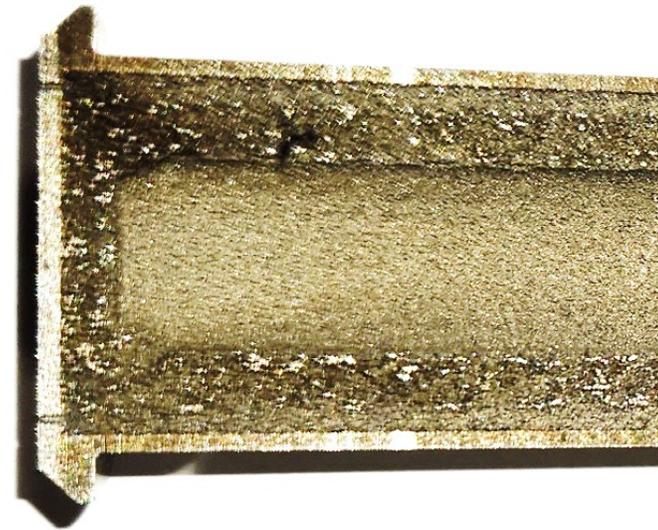
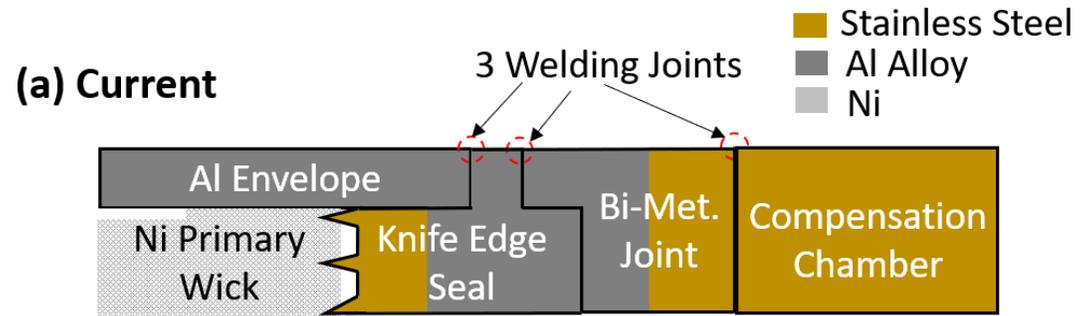


System Design Requirements



- 250W of additional heat rejection from a deployable radiator panel (DRP)
- 3DP Loop Heat Pipe (LHP)
- ESPA sized DRP
- High system conductance
- Small volume

- The 3DP evaporators eliminate the costly and labor-intensive knife edge seal found on current LHP evaporators
- The evaporator envelope, primary wick, and seal are printed as one piece
- The bottom figure shows the 3DP wick structure



**Single Piece
3DP
Evaporators**

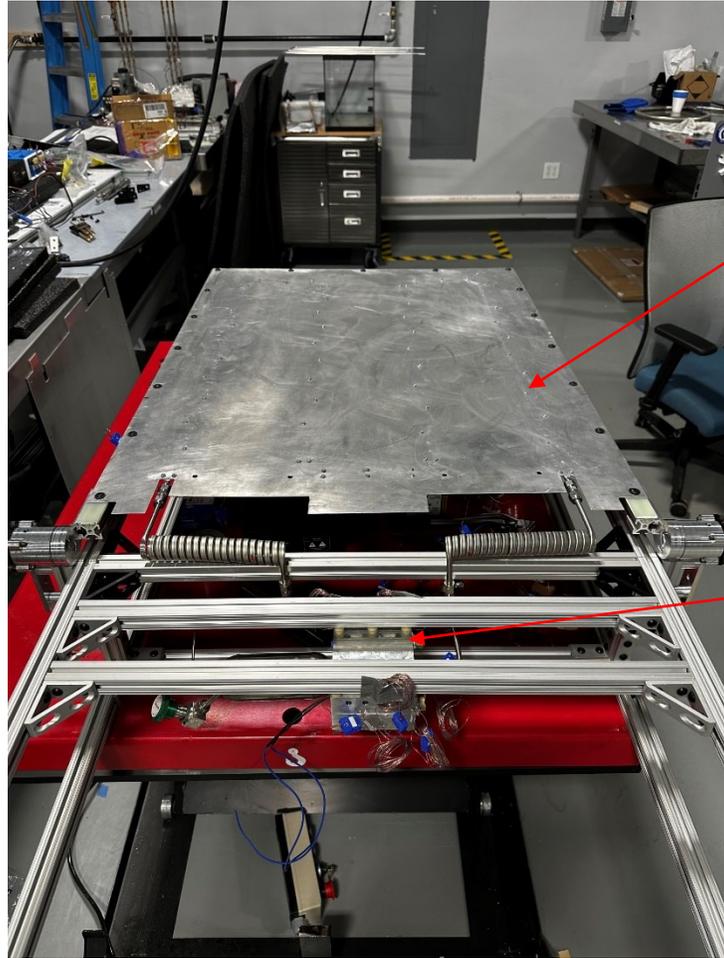


- 1" in diameter, 4" in length
- 316L SS primary wick and sleeve
- SS compensation chamber and secondary wick
- Manufactured with LPBF
- Single-piece component (Primary wick and sleeve)
- 6-micron pore radius
- Ammonia as the working fluid

- The panel is a 1/32" sheet of 6061-T6 aluminum
- The condenser line is 6061-T6 aluminum, 0.25" OD
- The bourdon coil hinge is constructed from 316L SS
- The radiative surface is coated in black paint
- Hinges are custom fabricated from 6061-T6 aluminum.
- G-10 is used to isolate the radiator panel from the support structure

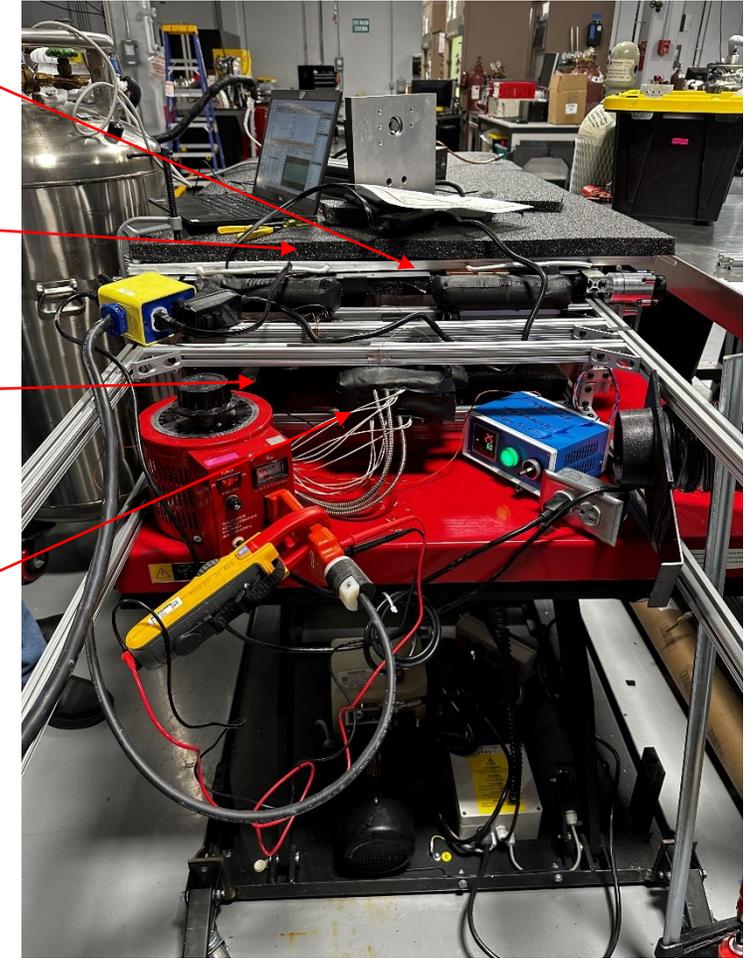


Ambient Condition Testing of the LHP and DRP



DRP

**Evaporator
Assembly**



Cold Plate

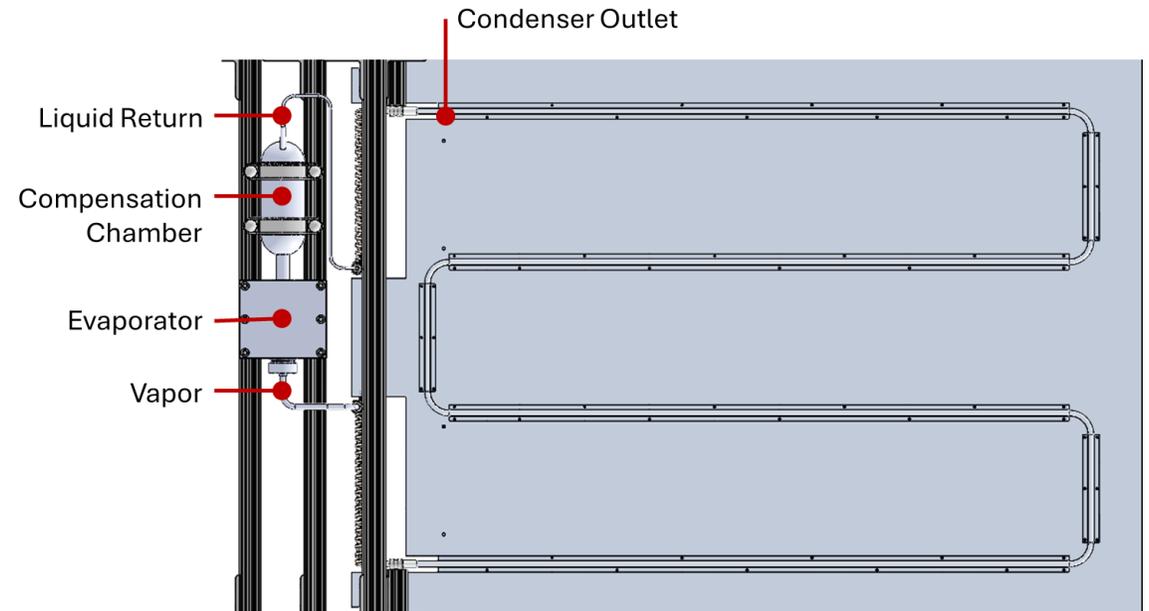
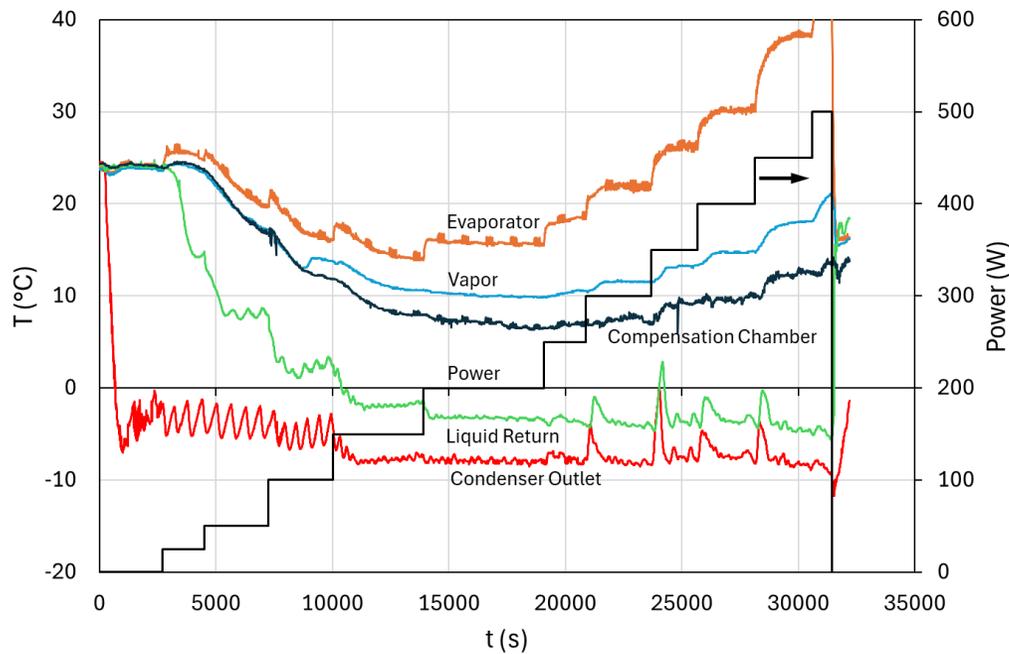
Insulation

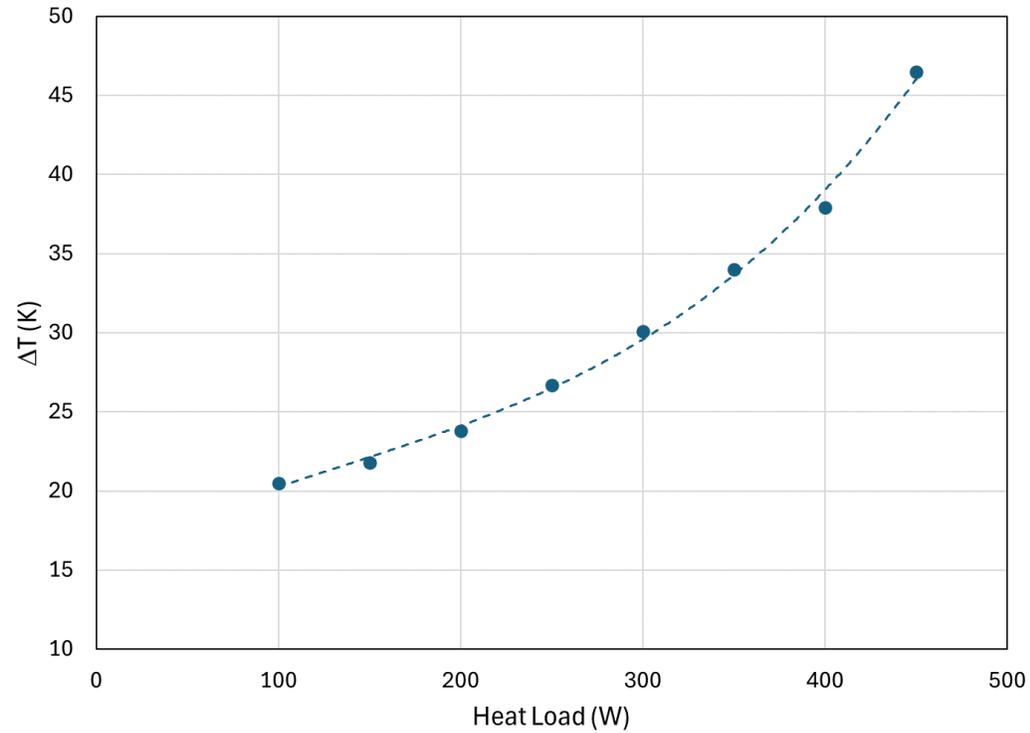
PLC

Heaters

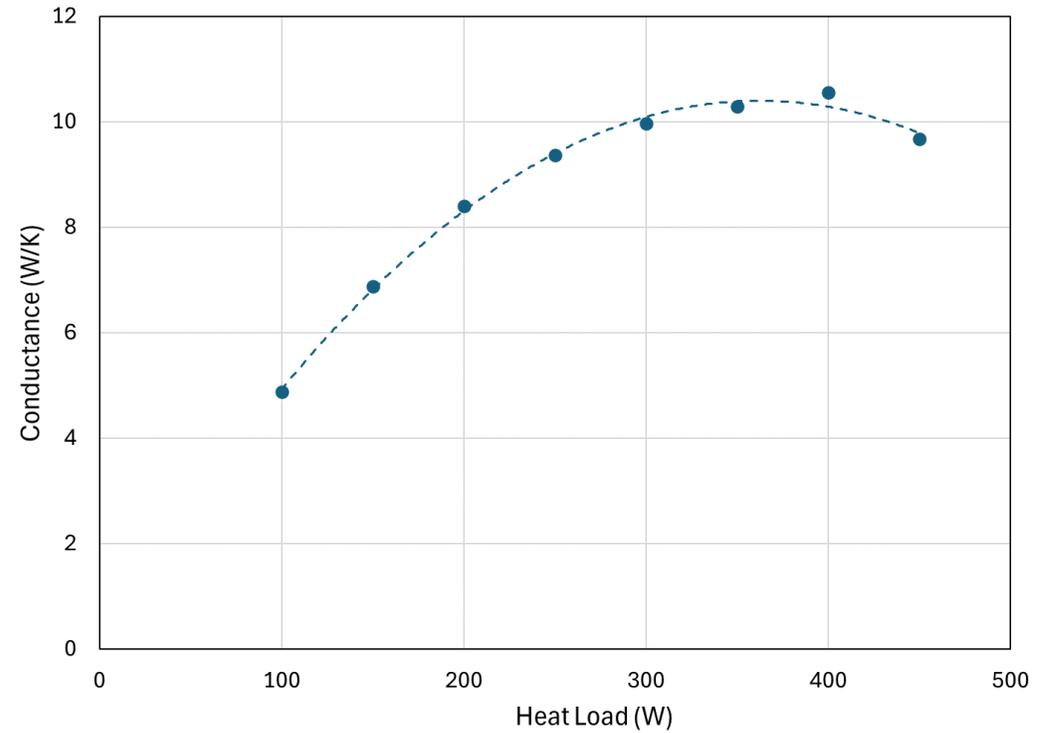
LHP laboratory test results:

- Loop starts at $\sim 25^\circ\text{C}$.
- The LHP was tested up to 500 W heat load.
- The loop conductance has a maximum of 10 W/K at a heat load of 300 W.

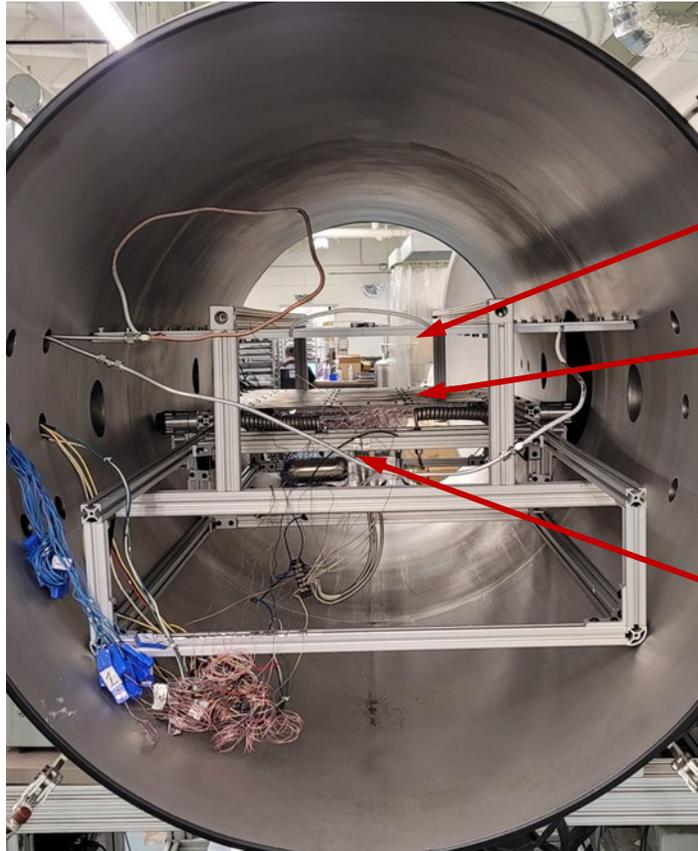




Temperature difference between evaporator surface and condenser outlet.



Heat removed for 1 K difference between evaporator surface and condenser outlet.



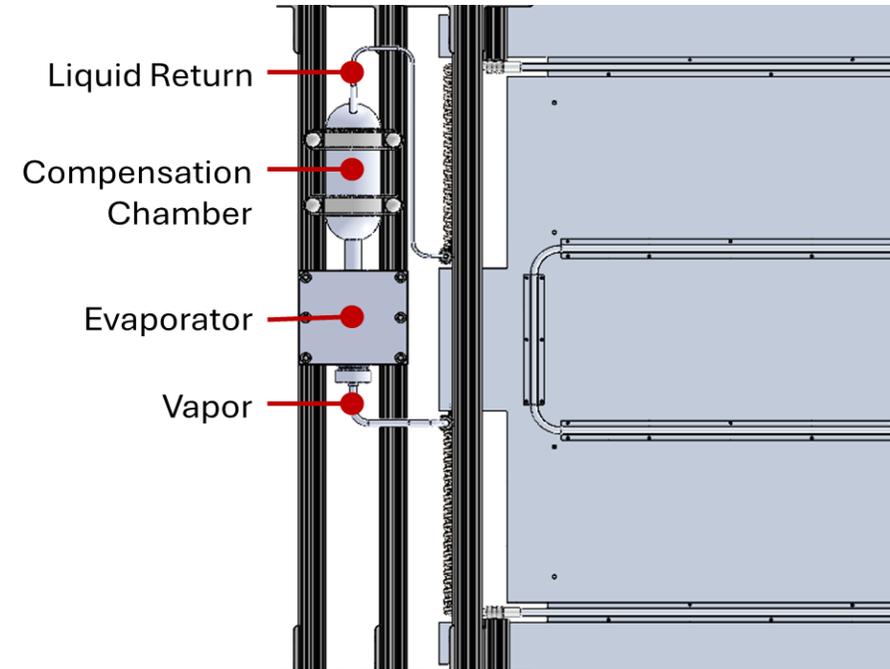
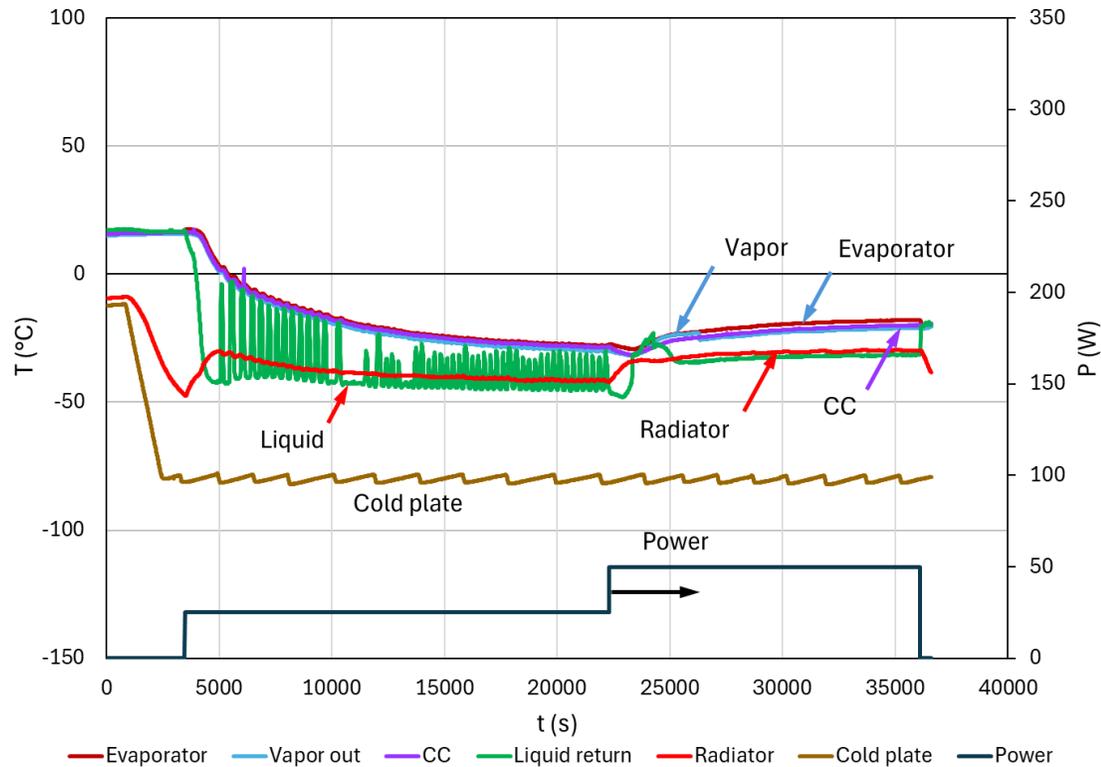
Cold plate

Radiator

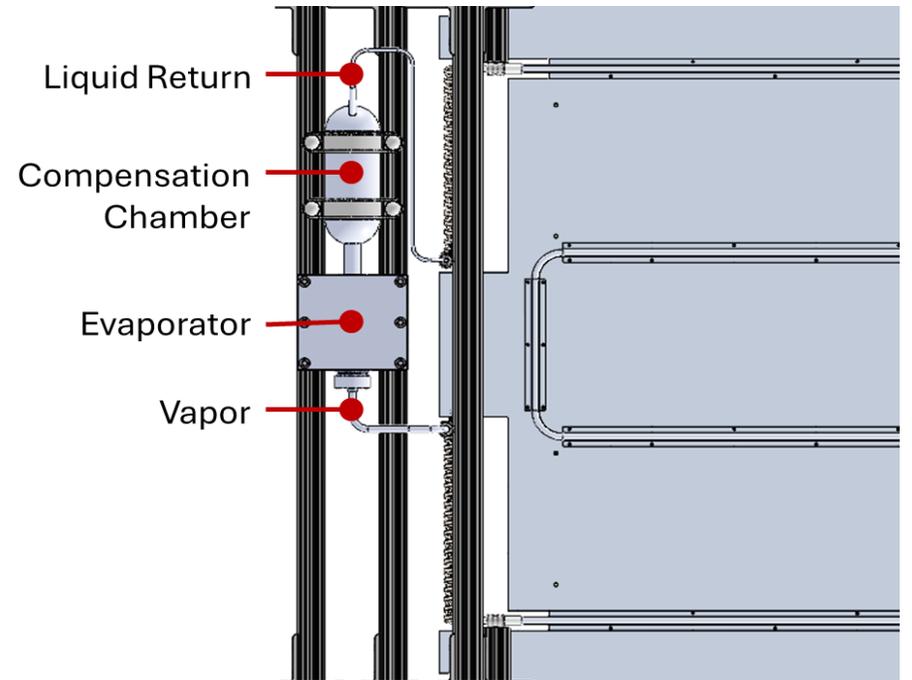
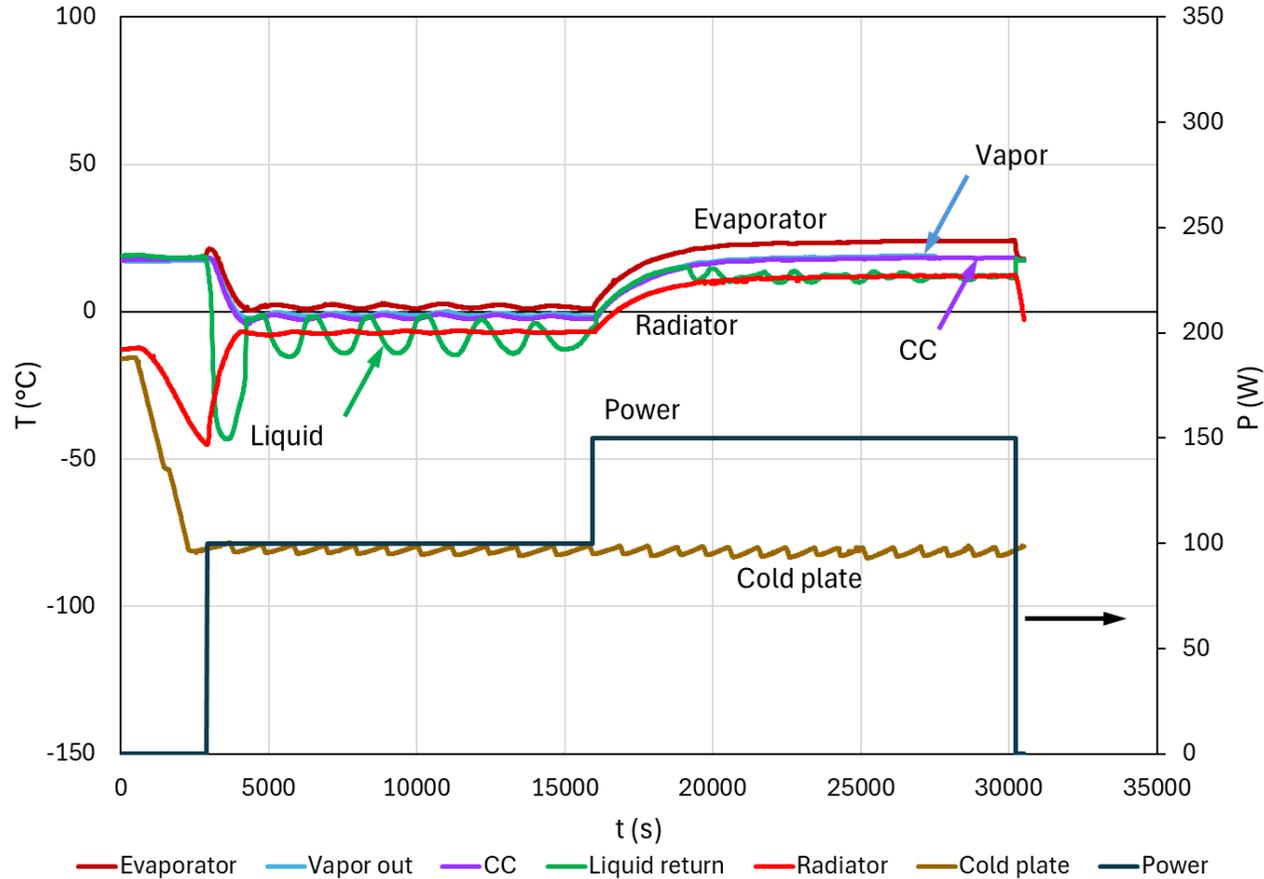
Compensation chamber and evaporator



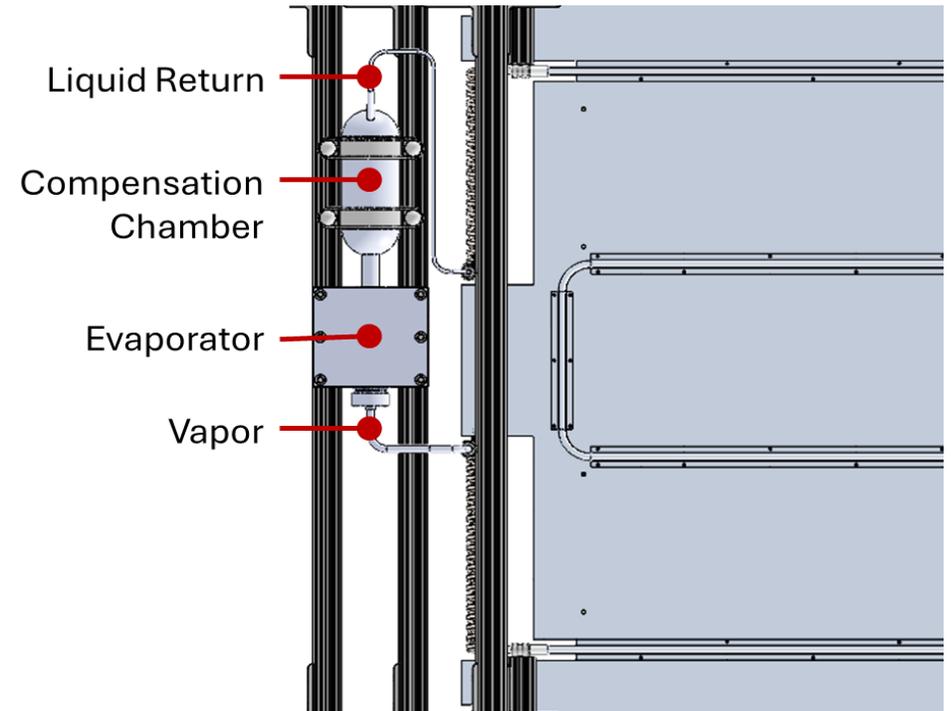
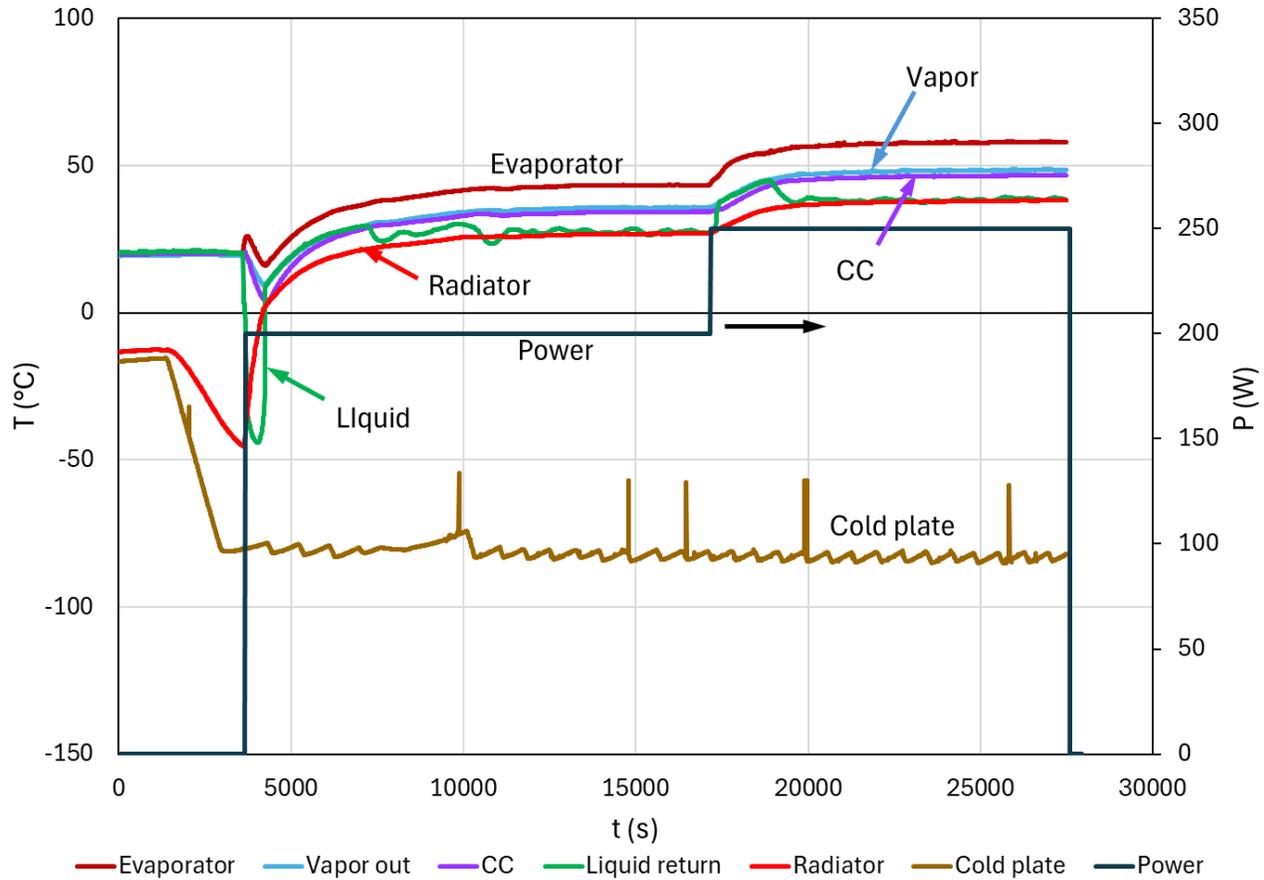
- The cold plate is held at -80 Celsius.
- Start up occurs at 25W



- Testing at 100W and 150W

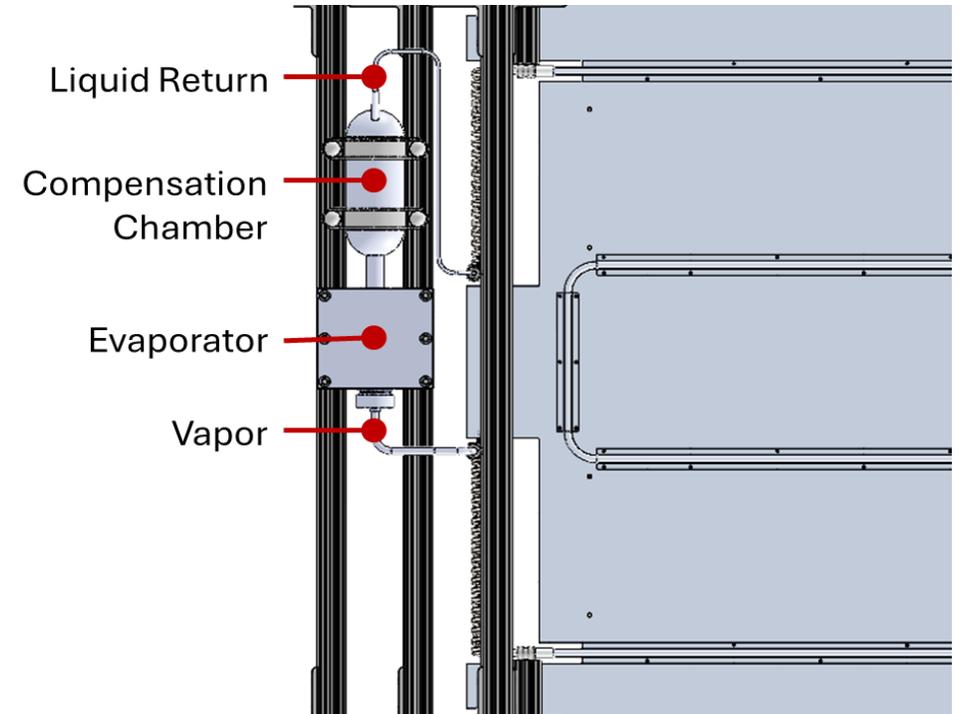
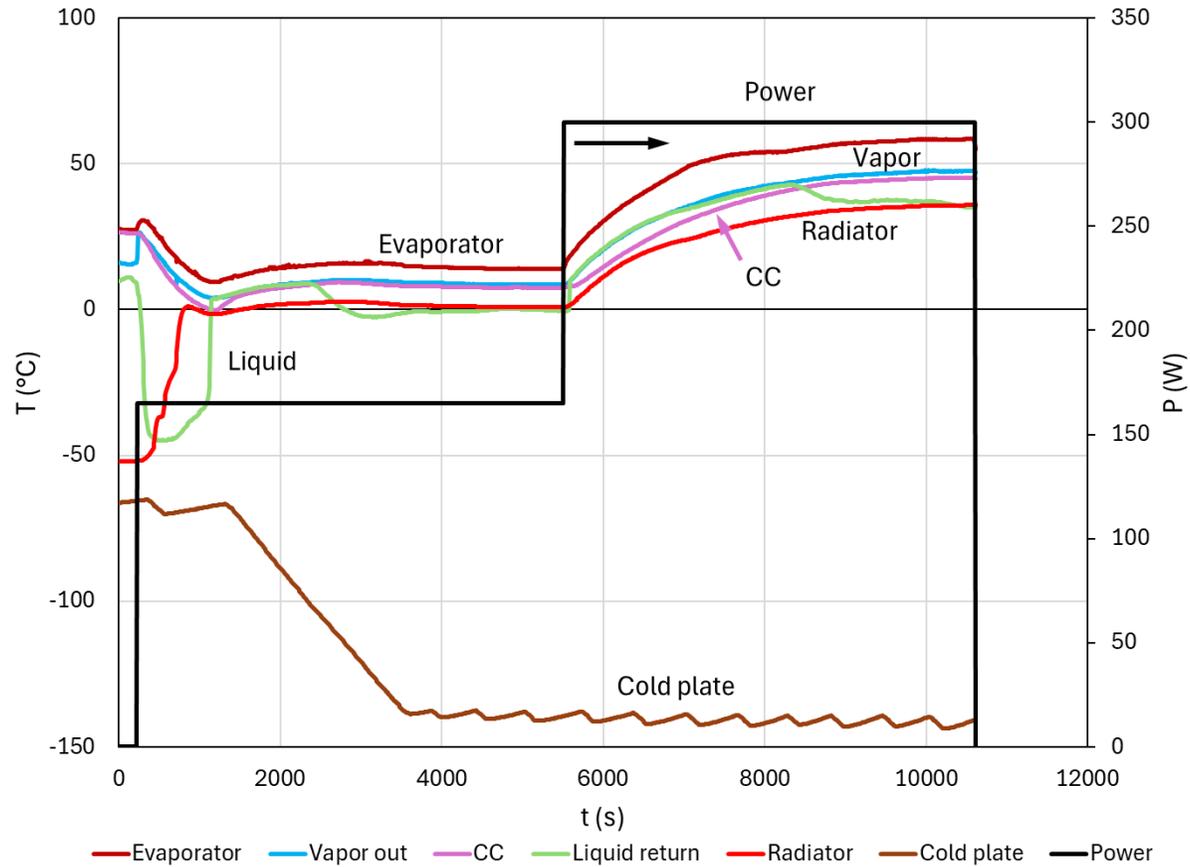


- Testing at 200W and 250W

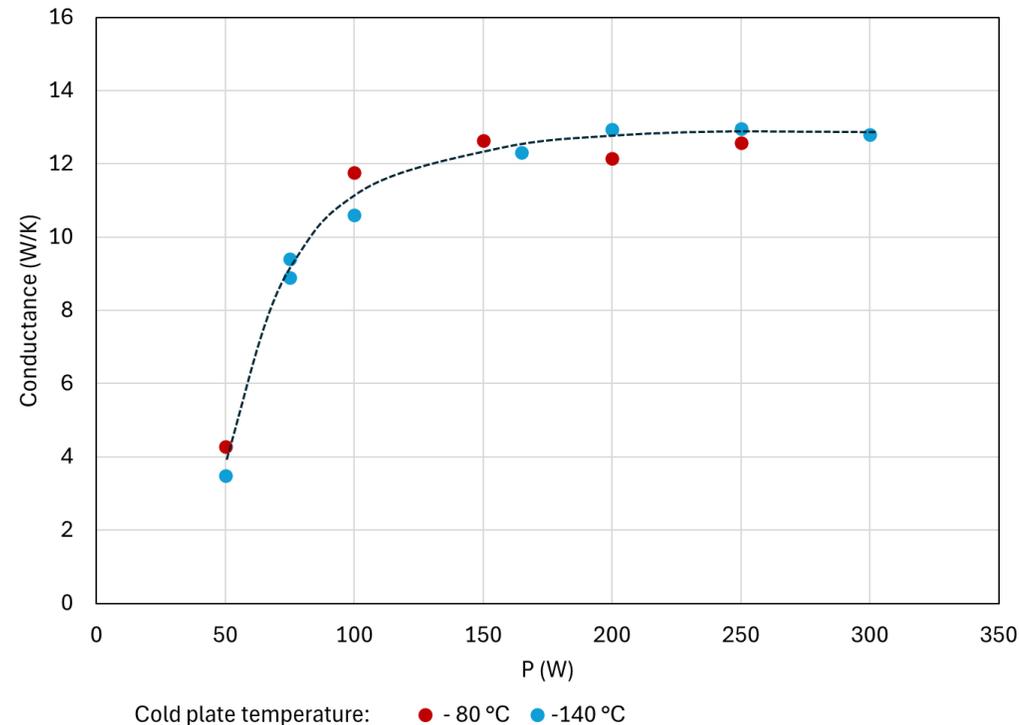


300W of Heat Rejection

- To reach 300W of heat rejection, the cold plate temperature had to be lowered to -140 Celsius.

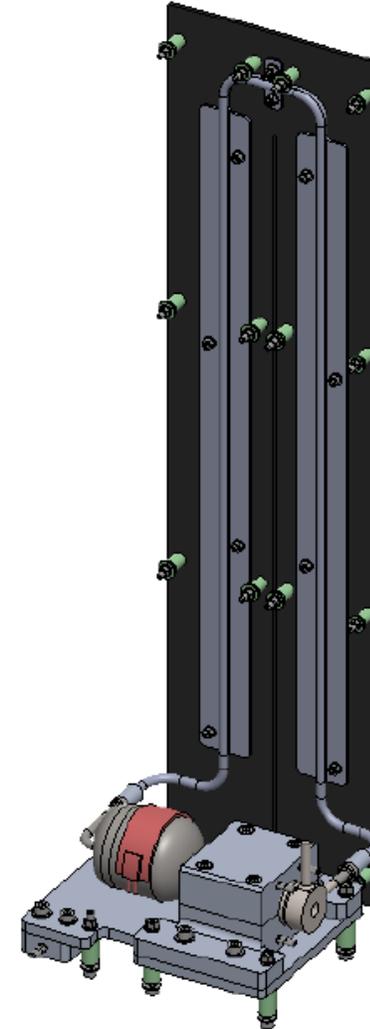


- Conductance was calculated from the measurements as the ratio of power load to evaporator to radiator temperature difference.
- The LHP reached constant conductance at ~150 W.
- The maximum conductance was 12.8 W/K



Next Steps

- ACT is developing new evaporators with a different primary wick and vapor groove structure to increase permeability and reduce dry-out.
- A scaled model is being constructed for a flight technology demonstration, in which the 3DP LHP will reject 15W of heat from a 3U CubeSat. This technology demonstration will occur in 2025.





Acknowledgments



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Questions



Thank you!